

C1206C223F2GECTU

Aliases (C1206C223F2GEC7800)

ESD SMD Comm COG, Ceramic, 0.022 uF, 1%, 200 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206



Click [here](#) for the 3D model.

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	36 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.6mm +/-0.20mm
B	0.5mm +/-0.25mm

Specifications	
Capacitance	0.022 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	200 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	45.4545 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2000

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